

In the Specification

At page 1, before line 1, please insert the heading and following paragraph:

RELATED APPLICATIONS

A1
This application is a divisional application of U.S. Application No. 09/003,670 filed on January 7, 1998.

In the Claims

Please cancel claims 1-17, and amend claim 18 as follows.

- A2*
18. (Amended) An apparatus for surface treating a semiconductor wafer comprising:

a surface treatment chamber; and

a source of radiation illuminating a semiconductor wafer disposed inside the chamber under ambient pressure and atmosphere with a radiation having a wavelength in a near infrared range sufficient to create a plurality of electron-hole pairs near a surface of the wafer and to desorb any contaminant adsorbed on the surface of the wafer.

A3
Please add the following claims:

- 27. A method for characterizing a semiconductor wafer comprising:

restoring an inversion condition at a surface of the wafer by illuminating the surface of the wafer with light; and

measuring an electrical characteristic of the wafer using the inversion condition as a reference point.

28. The method of claim 27 wherein the wafer comprises a p-type wafer.